

torney's Docket No.: 042390.P15858

<u>Patent</u>

## RESPONSE UNDER 37 C.F.R. § 1.116 EXPEDITED PROCEDURE EXAMINING GROUP 2826

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re Application of:				
	Vassoudevane Lebonheur, et al.	)	Examiner:	Victor A. Mandala
Application No: 10/612,764		)	Art Unit:	2826
Filed: June 30, 2003		)	Art Offit.	2020
For:	MOLD COMPOUND CAP IN A FLIP CHIP MULTI-MATRIX ARRAY PACKAGE AND PROCESS OF MAKING SAME	) ) ) )		
Mail Stop AF Commissioner for Patents				
P.O. Box 1450				
Alexandria, VA 22313-1450				
AMENDMENT AND RESPONSE AFTER FINAL ACTION				
<u>UNDER 37 C.F.R. § 1.116</u>				
Dear Sir: In response to the Office Action dated April 6, 2007, Applicants respectfully request that the above-identified application be amended as follows and that the following remarks be considered:				
FIRST-CLASS CERTIFICATE OF MAILING  I hereby certify that this correspondence is being deposited with the United States Postal Service as first-class mail with sufficient postage in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia, 22313-1450, on:				
June 5, 2007				
Date of Deposit Ariana C. Bates				
Name of Person Mailing Correspondence				
	Liano C/Sala		June 5	,2007
Signatu	ire (	Øa	t <b>y</b> l	

Vassoudevane Lebonheur, et al. Application No.: 10/612,764

Examiner: Victor A. Mandala Art Unit: 2826